SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 0.50mm ZIF FPO	C Sunk Into The Board Type Connector, R/A, SMT Type
CUSTOMER PROD.NO/DWG.NO:	
E&T PROD.NO:	6731K-XXXN-00X
APPROVAL SHEET NO:	
E&T DWG. NO./DOCUMENT:	6731K-XXXN-00X
	DEW A2

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL" WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES							



ENTERY INDUSTRIAL CO., LTD. E&T ELECTRONICS (DONG GUAN) CO., LTD. E&T ELECTRONICS (SU ZHOU) CO., LTD.

Title: Pitch 0.50mm ZIF FPC Sunk Into The Board Type Connector, R/A, SMT Type

Revised Max Lee Title: Pitch 0.50m			nm ZIF FPC Sunk Into The Board Type Connector, R/A, SMT Type		
A3 Rev	06.01,2012' Description	TOWN AND AND AN ANY AND			
Document No. 6731K-XXXN-00X			Prepared By: Josh Lee	Date: 07,21,2008'	
		N-00X	Checked By:	Date: (10) 70/7/	

GROUP AND TEST SEQUENCE

	Test of Examination -		Test Group									
			В	С	D	Е	F	G	Н	I	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,4	1,5	1,3	1,3	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	FPC Retention Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						3		2			
13	Resistance To Soldering Heat									2		
14	Steam Aging						2					
15	Salt Spray							3				
16	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE:

This specification covers the pitch 0.5 mm ZIF FPC connector series.

2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
0.50mm ZIF FPC Sunk Into The Board Type Connector, R/A, SMT Type	6731K-XXXN-00X

3. RATINGS:

Item	S	tandard
Rated Voltage (MAX.)	50 V	DC
Rated Current (MAX.)	0.5A	DC
Operating Temperature Range	-40 ⁰	C ~ +80 ⁰ C

^{*}Including terminal temperature rise

4.PERFORMANCE:

4-1 Electrical Performance

4- 1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 1 mA Max. Test Voltage: 20mV Max Test Method:EIA-364-06B	50 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 100V DC. Test Duration: 1 minutes.	Initial: 500 MΩ Min
	nesistance	Test Method:EIA-364-21C	Final: 100 M Ω Min.
4-1-3	Dielectric Strength	Test Voltage: 200V AC. Test Time: 60 sec. Test Method:EIA-364-09C	No Breakdown

4-2 Mechanical Performance

	Item	Test Condition	Requirement
4-2-1	FPC Retention Force	Test Speed: 25±3 mm/min.	0.02kgf (per pin) MIN
4-2-2	Terminal / Housing Retention Force	Test Speed: 25mm/min.	0.1kgf (Min)

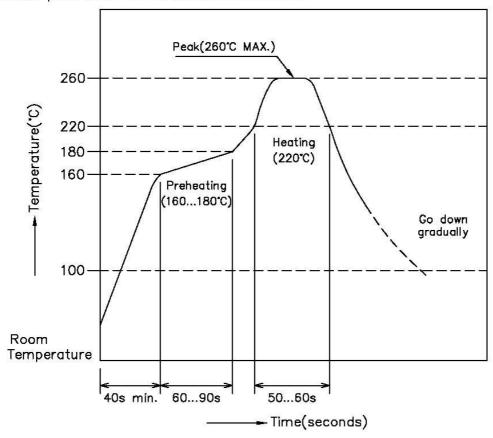
4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Insert and withdraw actuator up to 20cycles at the speed rate of less than 10 cycles/	Contact Re	sistance
4-3-1	Durability	minute.	Initial Value	\leq 50 m Ω
		Test Method:EIA-364-09C	Final Value	≤80 mΩ
		Amplitude : 1.5 mm Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-2	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method:EIA-364-28D	Contact Resistance	≦80 mΩ
		Test Method.LIA-304-20D	Discontinuity	1µsec
4-3-4	Heat	Temperature: 80±2℃ Duration: 96 hours	Appearance	No Damage
7-0-4	Resistance		Contact Resistance	≤80 mΩ
4-3-5	Cold	Temperature: $-40\pm2^{\circ}$ C Duration: 96 hours	Appearance	No Damage
4-5-5	Resistance		Contact Resistance	≦80 mΩ
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-6	Humidity	Duration: 96 hours Test Method:EIA-364-31B	Contact Resistance	≦80 mΩ
7-0-0	Trainialty		Insulation Resistance	\geq 100M Ω
			Dielectric Strength	Must meet 4-1-3

	Item	Test Condition	n	Requi	rement
4-3-7	Solder Ability	Soldering Time : 3±0.5 sec Solder Temperature : 245±5°C Test Method:EIA-364-52		Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5°C Test Method:EIA-364-56C		Appearance	No Damage
		Steam Aging Temperature: 985 Duration: 8 hours Solder Temperature: 235±5°C	±2 ℃	Appearance	No Damage
4-3-9	Steam Aging	I lest Method: FIA-364-17B		Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-10	Salt Spray	Chamber Temperature : 35±2°C Air Tank Temperature : 47±1°C Salt Solution : 5 ± 0.5% Duration : 48 hours		Appearance	No Damage
	oun opiny	Test Method:EIA-364-26B		Contact Resistance	\leq 80 m Ω
4-3-11	Temperature	5 cycles of : a) - 55 ±3℃ b) +25 ±3℃	30 minutes 30 minutes	Appearance	No Damage
4-3-11	Cycling	c)+ 85 $\pm 2^{\circ}\!\mathbb{C}$ Test Method:EIA-364-31B	30 minutes	Contact Resistance	\leq 80 m Ω

INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 255±5°C peak shall be 10 seconds maximum.



FPC /FFC Connector Front Flip Lock Type Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's ZIF FPC/FFC connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's ZIF FPC/FFC connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please add a stiffener on the flexible printed circuit (FPC/FFC) when you mount the connector onto FPC in order to prevent deformation of the FPC/FFC.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

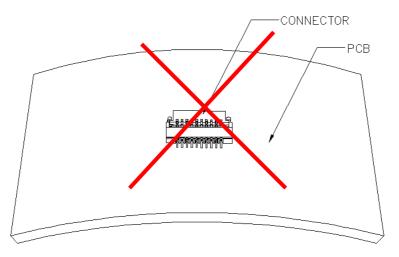


Figure 1.

3. Operation

FPC/FFC Insertion Procedure.

• 1) Connector installed on the board. Lift up the actuator(Lock). Use thumb or index finger. (see figure 2).

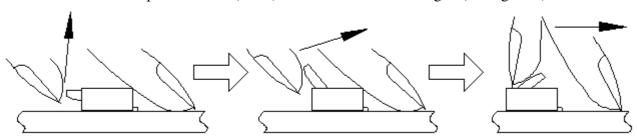


Figure 2.

• 2) Assure that the FPC/FFC is fully inserted parallel to mounting surface, with the exposed conductive traces facing down. (see figure 3).

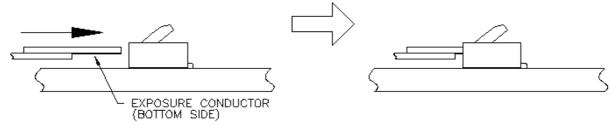


Figure 3.

• 3) Rotate down the actuator(Lock) until firmly closed. It is critical that the inserted FPC is not moved and remains fully inserted. Should the FPC be moved, open the actuator(Lock) and repeat the process, starting with Step 1(see figure 4).

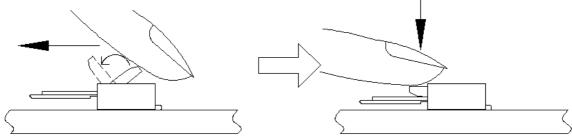


Figure 4.

FPC/FFC Removal.

1) Lift up the actuator(Lock). Carefully withdraw the FPC/FFC. (see figure 5).

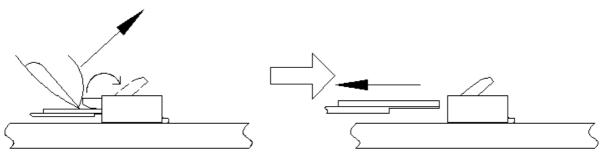


Figure 5.

4. Precautions When Inserting or Withdrawal FPC/FFC

• FPC/FFC to be insertion and withdrawal at an angle of about 15°, and the FPC/FFC should be inserted firmly all the way to the back. (see figure 6).

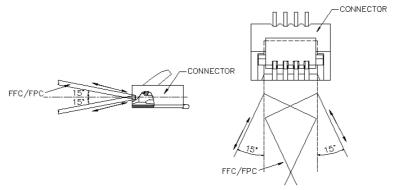


Figure 6.

- Do not apply excessive force or use any type of tool to operate the actuator(Lock).
- When locking the actuator(Lock), please make sure that the actuator is entirely closed by pressing on the entire actuator. Pushing the one specific point of the actuator may cause the actuator to be detached or damaged. When locking the longer actuator(Lock), please use two points to put pressure on locking. (see figure 7).

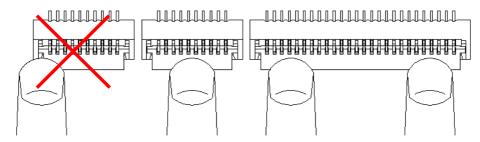
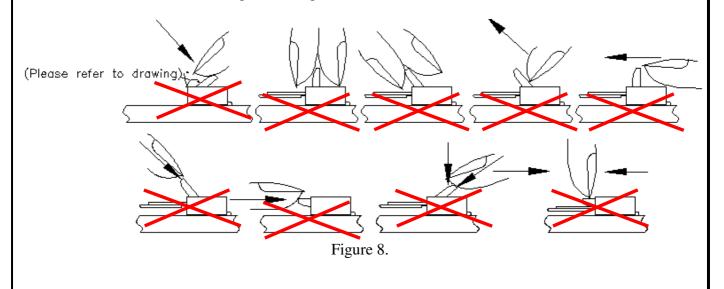


Figure 7.

- The connector will assure reliable performance when the actuator is open to an angle (please refer to drawing) maximum. Do not exceed this angle, as this may cause permanent damage to the connector. (see figure 8)
- Avoid grasping the actuator(Lock) with two fingers or lifting the actuator(Lock) with fingernail. (see figure 8)
- Do not apply force in the direction of arrows. Doing this may cause the actuator to be detached or damaged. (see figure 8).



• When inserting the FPC/FFC, do not forcefully rub against the surface beneath the connector insertion slot. Doing so will result in the FPC/FFC forcefully striking the contacts and this will cause contact deformation, peeling of the FPC/FFC conductors, and other irregularities. (see figure 9).

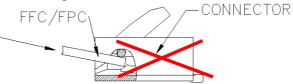
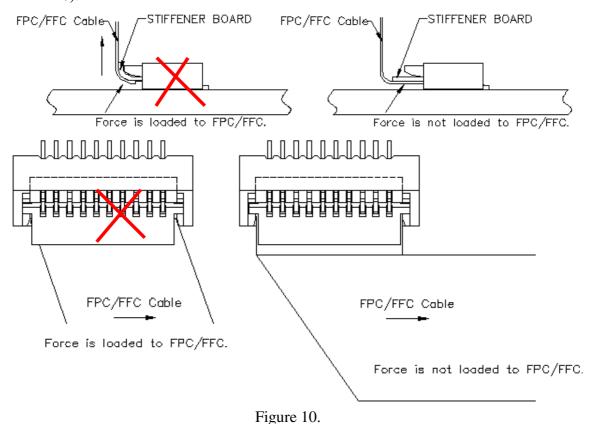


Figure 9.

- Do not apply any forces affecting soldered joints. Do not apply upward pull-force to the FPC/FFC close to the connector. (see figure 10).
- If necessary, please fix the FPC/FFC directly on the chassis. Also, please avoid pulling the FPC/FFC vertically or twisting the FPC back and force horizontally while it is inserted in the connector(see figure 10).
- Forming processing is conducted to FPC so as not to load force to connector. (see figure 10).



RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A2	RE201108011	AUG-10-2011	Max	ADD Handing Precautions
A3	RE201205010	JUN-01-2012	JIMMY	MATERIAL CHANGE